

METHOD FOR MANUFACTURING ELECTRONIC PARTS

ABSTRACT

A method for manufacturing electronic parts, which is characteristic in that it
5 permits reduction of contamination to the semi-cured adhesive layer formed on
semiconductor wafer and the cohesive sheet used therein is superior in adhesiveness for
example to the lead frame, the method comprising a semi-cured adhesive layer-forming
step of forming a semi-cured adhesive layer by coating a pasty adhesive entirely over
the rear face of a wafer and curing the pasty adhesive partially by radiation-ray
10 irradiation or heating into the sheet shape, a fixing step of fixing the semi-cured
adhesive layer formed on a wafer and a ring frame by bonding them to the cohesive
layer of a cohesive sheet, a dicing step of dicing the wafer together with the semi-cured
adhesive layer with a dicing blade into semiconductor chips, and a pick-up step of
picking up the chips carrying the semi-cured adhesive layer from the cohesive layer of
15 the cohesive sheet after radiation-ray irradiation, wherein the photopolymerization
initiator in the cohesive layer of the cohesive sheet has a particular property.

(no suitable figure)